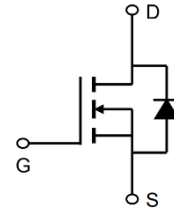


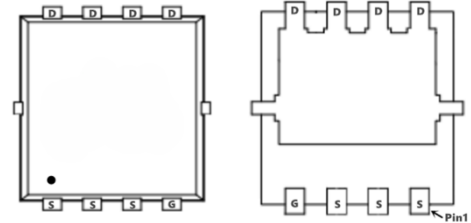
Description

The LM3D60N04 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



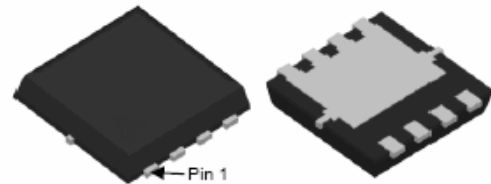
General Features

$V_{DS} = 40V$ $I_D = 60A$
 $R_{DS(ON)} < 15.5m\Omega @ V_{GS}=10V$



Application

Battery protection
 Load switch
 Uninterruptible power supply



Package Marking and Ordering Information

| Device | Device Marking | Device Package | Reel Size | Tape width | Quantity |
|-----------|----------------|----------------|-----------|------------|------------|
| LM3D60N04 | AP60N04DF | DFN3.3X3.3 | - | - | 5000 units |

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|-------------------------|---|------------|--------------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_C=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 60 | A |
| $I_D @ T_C=100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 26 | A |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 10 | A |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 8 | A |
| I_{DM} | Pulsed Drain Current ² | 100 | A |
| EAS | Single Pulse Avalanche Energy ³ | 31 | mJ |
| I_{AS} | Avalanche Current | 25 | A |
| $P_D @ T_C=25^\circ C$ | Total Power Dissipation ⁴ | 34.7 | W |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation ⁴ | 2 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient (Steady State) ¹ | 62 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | 3.6 | $^\circ C/W$ |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|--|--|------|-------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 40 | --- | --- | V |
| ∂BV _{DSS} /∂T _J | BVDSS Temperature Coefficient | Reference to 25°C , I _D =1mA | --- | 0.034 | --- | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V , I _D =20A | --- | 12.5 | 15.5 | mΩ |
| | | V _{GS} =4.5V , I _D =10A | --- | 14.5 | 20 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.0 | 1.5 | 2.5 | V |
| ∂V _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -5.64 | --- | mV/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =32V , V _{GS} =0V , T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =32V , V _{GS} =0V , T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V , V _{DS} =0V | --- | --- | ±100 | nA |
| g _{fs} | Forward Transconductance | V _{DS} =5V , I _D =20A | --- | 36 | --- | S |
| R _g | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | --- | 2.1 | 4.2 | Ω |
| Q _g | Total Gate Charge (4.5V) | V _{DS} =20V , V _{GS} =4.5V , I _D =12A | --- | 10.7 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 3.3 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 4.2 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =12V , V _{GS} =10V , R _G =3.3 I _D =6A | --- | 8.6 | --- | ns |
| T _r | Rise Time | | --- | 3.4 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 25 | --- | |
| T _f | Fall Time | | --- | 2.2 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | --- | 1314 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 120 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 88 | --- | |
| I _S | Continuous Source Current ^{1,5} | V _G =V _D =0V , Force Current | --- | --- | 42 | A |
| I _{SM} | Pulsed Source Current ^{2,5} | | --- | --- | 100 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =1A , T _J =25°C | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=25A
- 4.The power dissipation is limited by 150°C junction temperature
- 5 .The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Electrical and Thermal Characteristics

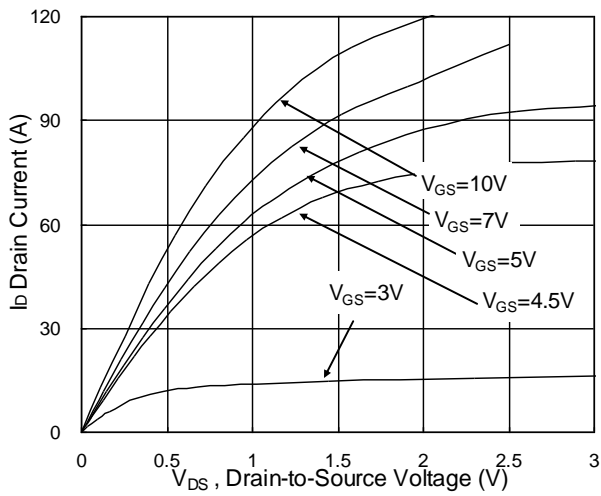


Fig.1 Typical Output Characteristics

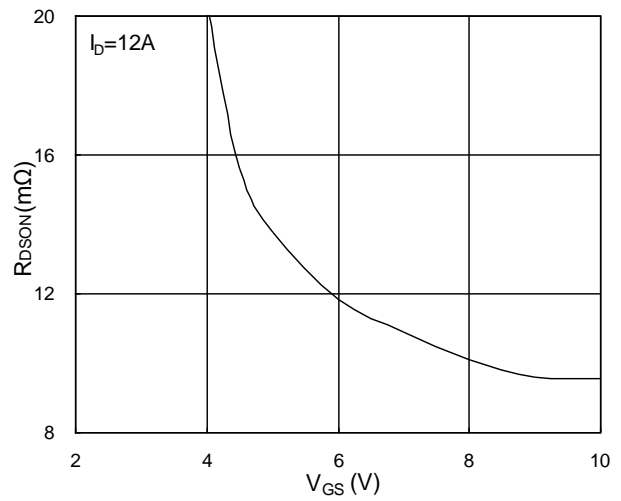


Fig.2 On-Resistance vs. G-S Voltage

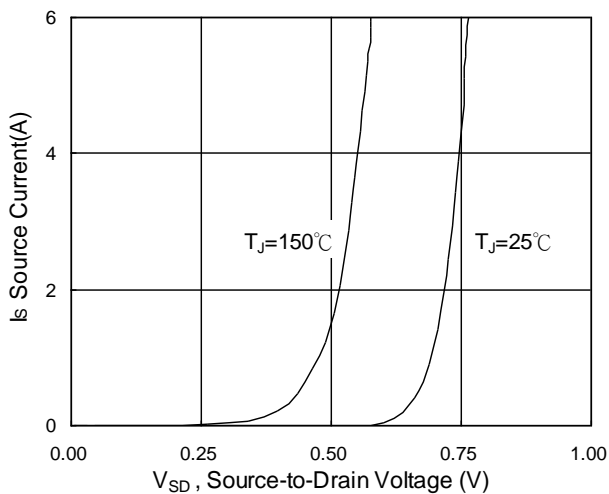


Fig.3 Forward Characteristics of Reverse

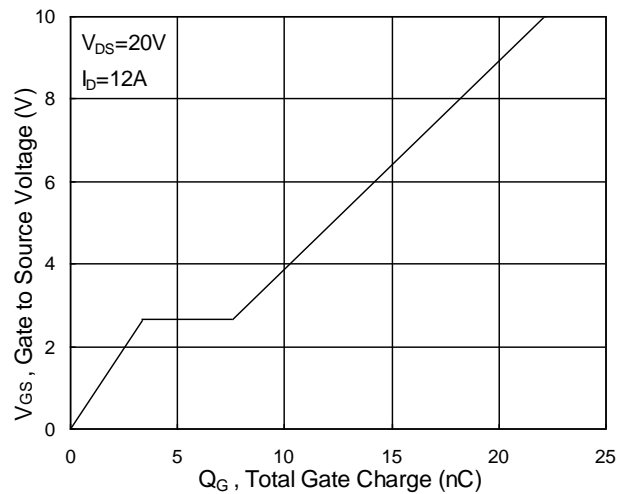


Fig.4 Gate-Charge Characteristics

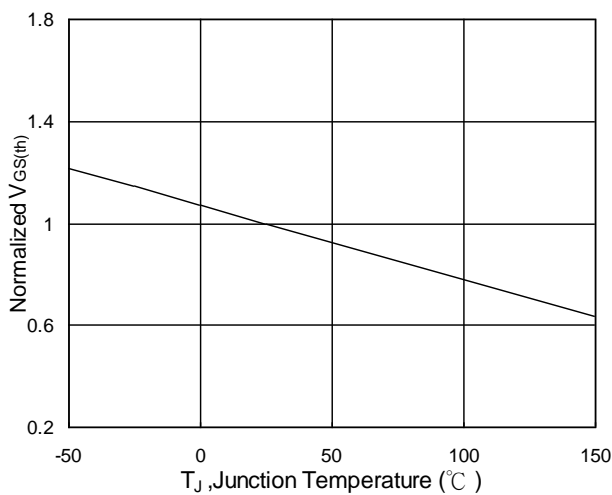


Fig.5 V_{GS(th)} vs. T_J

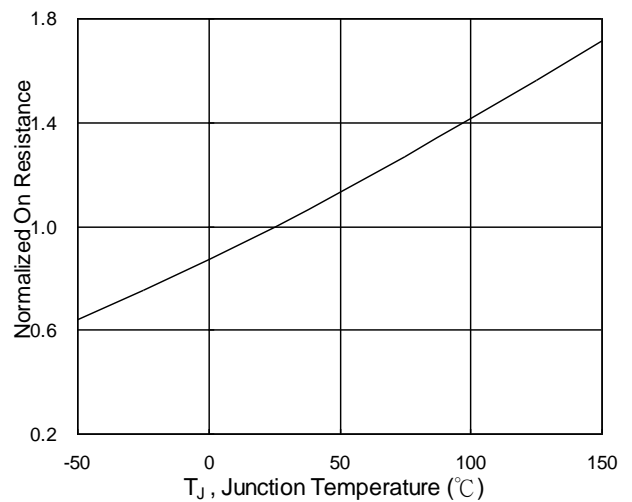


Fig.6 Normalized R_{DS(on)} vs. T_J

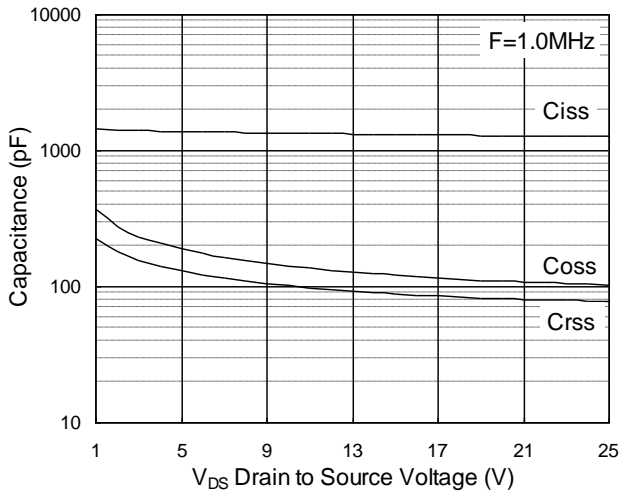


Fig.7 Capacitance

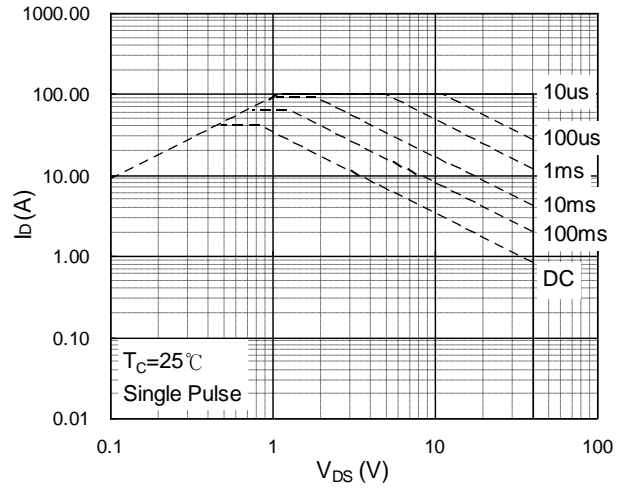


Fig.8 Safe Operating Area

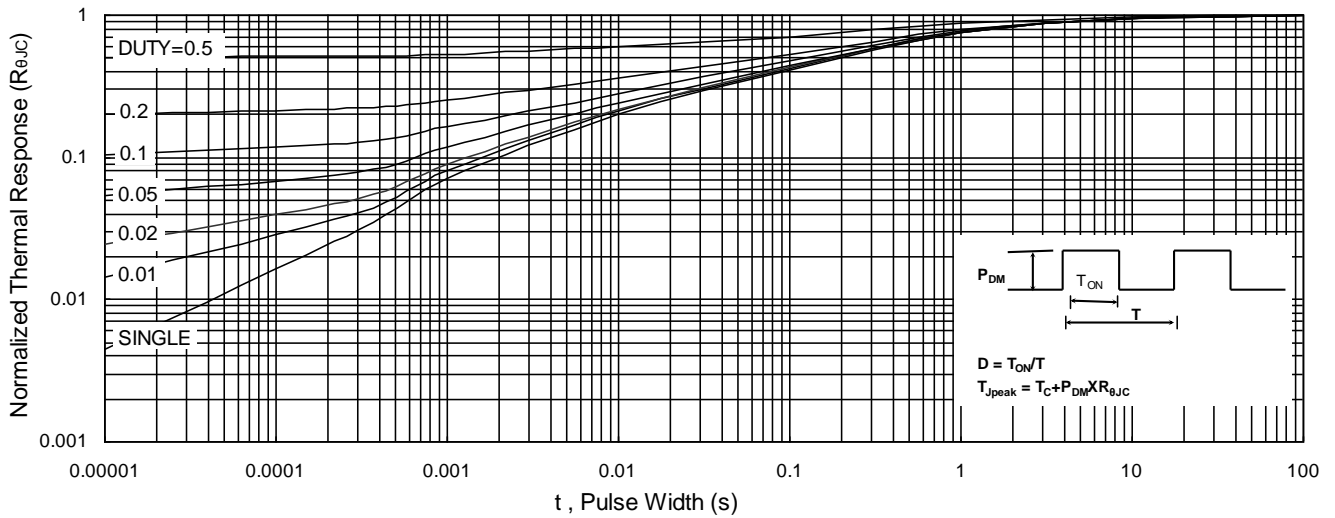


Fig.9 Normalized Maximum Transient Thermal Impedance

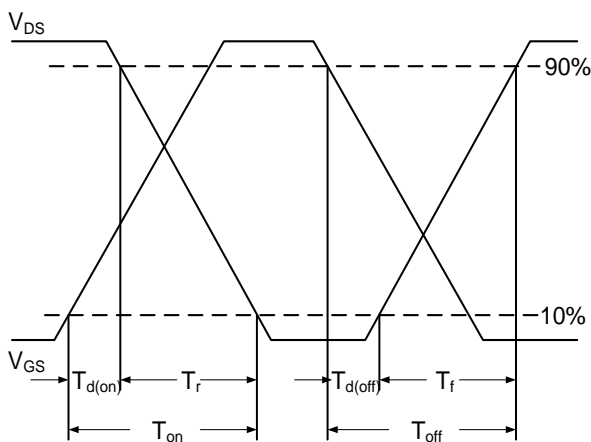


Fig.10 Switching Time Waveform

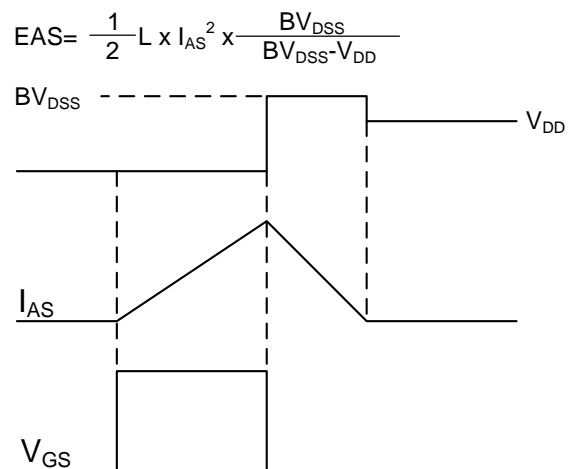
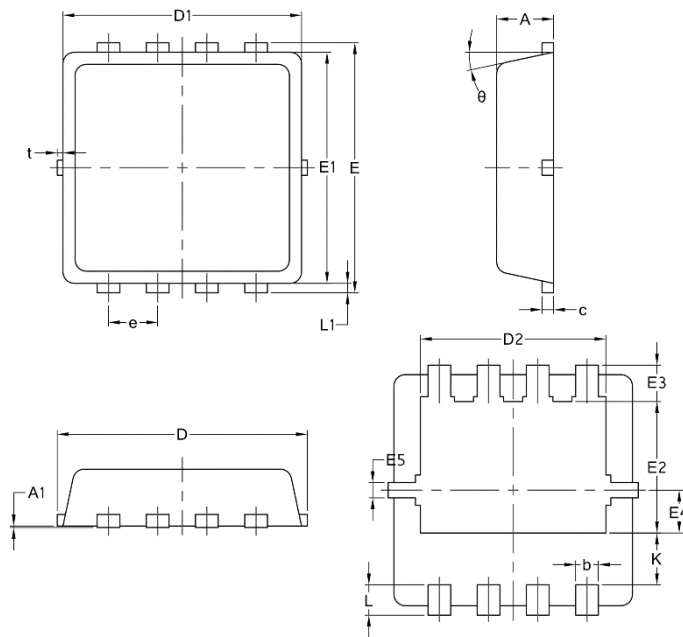


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-DFN3.3x3.3-JQ Single



| Symbol | Common | | |
|--------|--------|-------|------|
| | mm | | |
| | Mim | Nom | Max |
| A | 0.70 | 0.75 | 0.85 |
| A1 | / | / | 0.05 |
| b | 0.20 | 0.30 | 0.40 |
| c | 0.10 | 0.152 | 0.25 |
| D | 3.15 | 3.30 | 3.45 |
| D1 | 3.00 | 3.15 | 3.25 |
| D2 | 2.29 | 2.45 | 2.65 |
| E | 3.15 | 3.30 | 3.45 |
| E1 | 2.90 | 3.05 | 3.20 |
| E2 | 1.54 | 1.74 | 1.94 |
| E3 | 0.28 | 0.48 | 0.65 |
| E4 | 0.37 | 0.57 | 0.77 |
| E5 | 0.10 | 0.20 | 0.30 |
| e | 0.60 | 0.65 | 0.70 |
| K | 0.59 | 0.69 | 0.89 |
| L | 0.30 | 0.40 | 0.50 |
| L1 | 0.06 | 0.125 | 0.20 |
| t | 0 | 0.075 | 0.13 |
| Φ | 10 | 12 | 14 |